Max PCB Size 480×345mm BGA Repair Station Total Power 4800W Solution for PCB Rework and Electronic Component Maintenance

Our Product Introduction

Basic Information

- Brand Name: WDS
- Certification: CE
- Model Number: WDS-S7
- Minimum Order Quantity: 1SET



Product Specification

- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±3°C Accuracy
- Thermocouple Ports: 1 Pc
- Power Supply: AC220V±10%, 50/60Hz
- Max PCB Size: 480×345mm
- Applicable Chip Size: 1×1mm – 60×60mm
- Total Power: 4800W
- Weight: Approx. 34KG

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Product Description

Product Description:

The Manual BGA Rework Station is a high-performance, reliable solution designed specifically for professionals involved in motherboard repair and other intricate electronic component tasks. This advanced rework station combines precision, power, and ease of use to deliver outstanding results in the delicate process of repairing and reworking Ball Grid Array (BGA) components on motherboards and other printed circuit boards (PCBs).

One of the standout features of this Manual BGA Rework Station is its robust total power of 4800W. This powerful heating capability ensures rapid and even heat distribution, which is critical when working with sensitive electronic components. The efficient heat control enables technicians to perform motherboard repair tasks with greater confidence and precision, reducing the risk of damage to the PCB or the components themselves.

The station is engineered to accommodate a wide range of chip sizes, from as small as 1×1mm to as large as 60×60mm. This versatility makes it suitable for a variety of applications, whether you're working on tiny chips or larger BGA components. Additionally, the maximum PCB size supported by this rework station is 480×345mm, providing ample workspace for most standard motherboards and other electronic boards. This capacity allows technicians to handle a broad spectrum of repair jobs without the need for multiple machines.

Ease of operation is a core design principle of this Manual BGA Rework Station. Despite its advanced capabilities, the station is user-friendly, making it accessible for both seasoned professionals and those new to motherboard repair. The intuitive controls and clear interface facilitate quick setup and adjustment, allowing technicians to focus on the repair process itself rather than struggling with complicated equipment. This ease of operation significantly enhances productivity and helps minimize downtime.

To ensure precise temperature monitoring and control, the rework station is equipped with one thermocouple port. This feature allows for accurate measurement of the temperature at critical points during the rework process, ensuring that components are heated to the optimal temperature without overheating. Accurate temperature control is essential in motherboard repair to prevent damage to delicate chips and solder joints.

Weighing approximately 34 kilograms, this Manual BGA Rework Station strikes a balance between portability and stability. Its weight ensures that the unit remains stable during operation, preventing movement that could disrupt the delicate rework process. At the same time, it is still manageable enough to be moved between workstations or transported as needed, providing flexibility in various repair environments.

In summary, the Manual BGA Rework Station is an indispensable tool for anyone involved in motherboard repair and electronic component rework. Its powerful 4800W heating system, wide chip size compatibility, and ability to handle sizable PCBs make it a versatile and efficient choice. The single thermocouple port facilitates precise temperature control, while the approximately 34KG weight ensures a stable yet portable setup. Most importantly, its easy operation design allows technicians to perform complex motherboard repair tasks with confidence and efficiency.

Whether you are repairing damaged motherboards, replacing BGA chips, or performing routine maintenance, this Manual BGA Rework Station offers the perfect combination of power, precision, and user-friendliness. It is an excellent investment for electronics repair shops, service centers, and individual technicians aiming to enhance their repair capabilities and deliver high-quality results.

Features:

Product Name: Manual BGA Rework Station

Thermocouple Ports: 1 Pc

Applicable Chip Size: 1×1mm – 60×60mm

Power Supply: AC220V±10%, 50/60Hz

Temperature Control: Closed-loop K-type Thermocouple with ±3°C Accuracy

Heating Zones: 3 heating zone with Upper & Lower Independent Heating

Weight: Approx. 34KG

Functionality: Ideal for precise soldering and rework station applications

Application: Suitable for use as a soldering station and rework station

Technical Parameters:

Thermocouple Ports	1 Pc
Power Supply	AC220V±10%, 50/60Hz
Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±3°C Accuracy
Weight	Approx. 34KG
Applicable Chip Size	1×1mm – 60×60mm
Total Power	4800W
Max PCB Size	480×345mm
Additional Features	PLC control, chip repair, 3 heating zone

Applications:

The WDS-S7 Manual BGA Rework Station by WDS is a highly efficient and reliable tool designed for precision electronic repair and manufacturing processes. Certified with CE, this station ensures safety and quality standards, making it suitable for professional use in various environments. Weighing approximately 34KG, it is sturdy yet manageable, providing stability during delicate operations. The

station operates on an AC220V±10%, 50/60Hz power supply with a total power consumption of 4800W, delivering robust performance for demanding tasks.
One of the standout features of the WDS-S7 is its advanced temperature control system. Equipped with a closed-loop K-type thermocouple and upper & lower independent heating, it offers precise temperature management with an accuracy of ±3°C. This ensures optimal heating conditions for different components, minimizing the risk of damage during the rework process. The station includes 1 thermocouple port, allowing for accurate temperature monitoring and control throughout the operation.
The WDS-S7 is especially suited for applications involving BGA (Ball Grid Array) components, where precision is critical. Its 3 heating zone design provides uniform heat distribution across the component, facilitating efficient desoldering and mounting processes. This multi-zone heating capability allows technicians to carefully remove and replace BGAs without causing thermal stress to surrounding parts, making it ideal for repairing circuit boards, reflowing solder joints, and prototyping new designs.
In terms of application occasions and scenarios, the WDS-S7 Manual BGA Rework Station is perfect for electronics repair shops, manufacturing lines, and research and development labs. It is invaluable for tasks such as desoldering faulty BGA chips from motherboards, mounting new components with high precision, and reworking defective solder joints on complex PCBs. Whether used for small-scale repairs or large production runs, this station's accurate temperature control and 3 heating zone system ensure high-quality results every time.
Moreover, the WDS-S7's user-friendly interface and reliable performance make it suitable for both experienced technicians and those new to BGA rework. Its ability to handle various heating profiles enhances its versatility across different electronic devices, from smartphones and laptops to industrial equipment. With a minimum order quantity of 1SET, this product is accessible for individual professionals or companies looking to upgrade their rework capabilities.

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